3mm Round LED Lamps

PART NO.: L-03K2C141C11-01



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

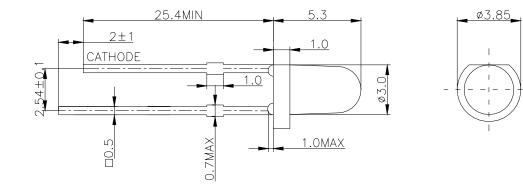
Features

- •Low power consumption
- •Excellent product quality and reliability
- •Lead-free device.

Applications

- Electronic signs and signals
- Bright ambient lighting conditions
- Backlight
- General purpose indicatiors





Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ± 0.25 unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.5.The design and working Current for Led is not less than2mA.

Device Selection Guide

Part No.	Cł	Lens color		
L-03K2C141C11-01	Material	Emitted color		
	GaP	Kelly	Water Clear	

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	Pd	50	mW	
Forward Current	lf	30	mA	
Peak Forward Current*1	I FP	100	mA	
Reverse Voltage	Vr	5	V	
Operating Temperature	Topr	-40°C To +85°C		
Storage Temperature	Tstg	-40°C To +85°C		
Soldering Temperature*2	Tsol	260°C For 5 Seconds		

Notes:

*1: Pulse width≤0.1ms, Duty cycle≤1/10

*2:1.6mm below package base.

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min.	Тур.	Max	Unit	Test Conditions
Forward Voltage	VF	1.80	2.10	2.60	V	IF=20mA
Reverse Current	Ir		_	10	μA	VR=5V
Dominant Wavelength	λd	565	570	575	nm	IF=20mA
Peak Wavelength	λP		565		nm	IF=20mA
Spectral line Half-width	Δλ	_	15	_	nm	IF=20mA
Luminous Intensity	lv	600	1300	2500	mcd	IF=20mA
Power Angle	2 0 1/2	_	25	_	Deg.	IF=20mA

Remarks:

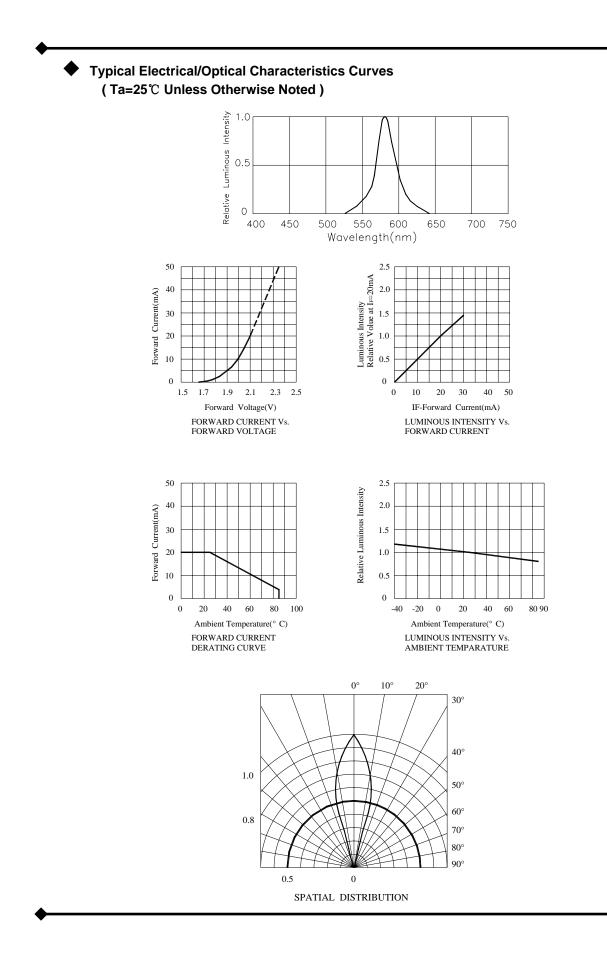
If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or dominant wavelength), the typical accuracy of the sorting process is as follows:

1.Dominant Wavelength:+/-1nm

2.Chromatic Coordinates:+/-0.01

3. Luminous Intensity: +/-15%

4. Forward Voltage: +/-0.1V



• CAUTIONS:

1.Lead Forming & Assembly

- Lead forming or bending must be done before soldering, at normal temperature.
- During lead forming, the leads should be bent at a point at least 3mm from the base of LED lens.
- Do not use the base of the lead frame as a fulcrum during lead forming.
- Avoid bending the leads at the same point more than once.

• During assembly on PCB, use minimum clinch force possible to avoid excessive mechanical

stress.

2.Cleaning:

• Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LEDs if necessary. **3.Storage**

- The storage ambient for the LEDs should not exceed 30°C temperature or 70% relative humidity.
- It is recommended that LEDs out of their original packaging are used within three months. For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

4.ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent of ESD damage.

- All devices, equipment, and machinery must be properly grounded.
- Use a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- Maintain a humidity level of 50% or higher in production areas.
- Use anti-static packaging for transportation and storage.